Title (en)

THERMAL LINK

Title (de)

THERMOSICHERUNG

Title (fr)

COUPE-CIRCUIT THERMIQUE

Publication

EP 2471083 B1 20160427 (DE)

Application

EP 11749108 A 20110726

Priority

- DE 102010038401 A 20100726
- EP 2011062793 W 20110726

Abstract (en)

[origin: WO2012016882A1] In order to provide a method for isolating a circuit and a thermal link, wherein the link has a very low resistance and is suitable for high currents, in particular very high short load currents, and also has a high degree of reliability, in particular under difficult conditions, such as thermal and mechanical loading which lasts for a relatively long time, for example, the invention proposes that, during the phase transition of the material of the fusible element (10) from the solid to the liquid state, the volume of the fusible element (10) increases and the pressure increases and, owing to the increase in volume and the increase in pressure, the fusible element (10) is dislodged so as to break the electrical connection.

IPC 8 full level

H01H 37/76 (2006.01); **H01H 85/06** (2006.01); **H01H 85/12** (2006.01)

CPC (source: EP KR US)

B22D 41/015 (2013.01 - EP US); **H01H 37/32** (2013.01 - US); **H01H 37/76** (2013.01 - KR); **H01H 37/761** (2013.01 - EP US); **H01H 85/06** (2013.01 - EP KR US); **H01H 85/12** (2013.01 - EP KR US); H01H 85/0411 (2013.01 - US); H01H 85/08 (2013.01 - US); H01H 2037/768 (2013.01 - EP US); H01H 2085/0412 (2013.01 - US); H01H 2085/0414 (2013.01 - US)

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)

DE 102010038401 A1 20120126; **DE 102010038401 B4 20131114**; BR 112013001814 A2 20160531; BR 112013001814 B1 20201006; CN 103038849 A 20130410; CN 103038849 B 20150812; EP 2471083 A1 20120704; EP 2471083 B1 20160427; ES 2579004 T3 20160803; HU E029705 T2 20170328; JP 2013535781 A 20130912; JP 5723451 B2 20150527; KR 101539641 B1 20150728; KR 20130037726 A 20130416; US 2013234822 A1 20130912; US 9899171 B2 20180220; WO 2012016882 A1 20120209

DOCDB simple family (application)

DE 102010038401 A 20100726; BR 112013001814 A 20110726; CN 201180037010 A 20110726; EP 11749108 A 20110726; EP 2011062793 W 20110726; ES 11749108 T 20110726; HU E11749108 A 20110726; JP 2013521104 A 20110726; KR 20137004794 A 20110726; US 201113811700 A 20110726